(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization
International Bureau

(43) International Publication Date
14 March 2013 (14.03.2013)

WIPO | PCT

(10) International Publication Number
WO 2013/035019 A2

(51) International Patent Classification:
H01L 21/687 (2006.01)

(21) International Application Number:
PCT/IB2012/054440

(22) International Filing Date:
29 August 2012 (29.08.2012)

(25) Filing Language: English

(26) Publication Language: English

(30) Priority Data:
13/228,980 9 September 2011 (09.09.2011) US

(71) Applicant *(for all designated States except US)*: **LAM RESEARCH AG** [AT/AT]; SEZ-Strasse 1, A-9500 Villach (AT).

(71) Applicant *(for BZ only)*: **LAM RESEARCH CORPORATION** [US/US]; 4650 Cushing Parkway, Fremont, California CA-94538 (US).

(72) Inventors; and
(75) Inventors/Applicants *(for US only)*: **TSCHINDERLE, Ulrich** [AT/AT]; Goriach 29, A-9613 Feistritz/Gail (AT). **GLEISSNER, Andreas** [AT/AT]; Villacher Straße 5, A-Radenthein 9545 (AT). **WIRNSBERGER, Thomas** [AT/AT]; Lexhöhe 23, A-9871 Seeboden (AT). **OBWEGER, Rainer** [AT/AT]; Lind im Drautal 198, A-9753 Lind im Drautal (AT).

(74) Agent: **KONTRUS, Gerhard**; c/o Lam Research AG, SEZ-Strasse 1, A-9500 Villach (AT).

(81) Designated States *(unless otherwise indicated, for every kind of national protection available)*: AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.

(84) Designated States *(unless otherwise indicated, for every kind of regional protection available)*: ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

[Continued on next page]

(54) Title: APPARATUS FOR TREATING SURFACES OF WAFER-SHAPED ARTICLES

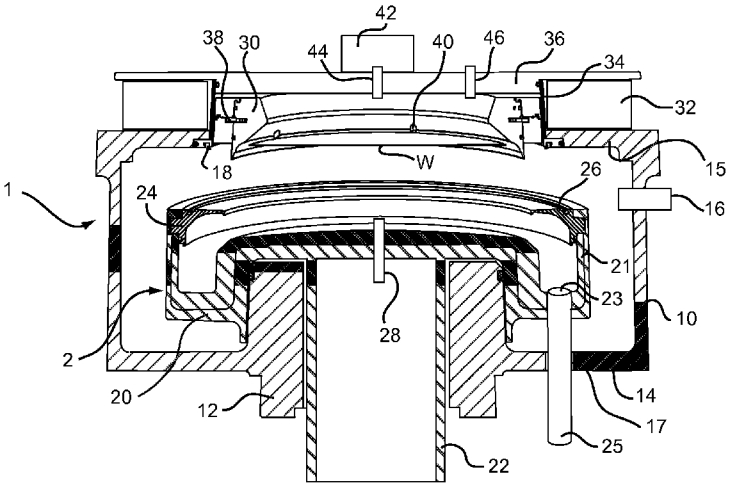


Fig. 1

(57) Abstract: A device for processing wafer-shaped articles comprises a closed process chamber. The closed process chamber comprises a housing providing a gas-tight enclosure, a rotary chuck located within the closed process chamber and adapted to hold a wafer shaped article thereon, and an interior cover disposed within said closed process chamber. The interior cover is movable between a first position in which the rotary chuck communicates with an outer wall of the closed process chamber, and a second position in which the interior cover seals against an inner surface of the closed process chamber adjacent the rotary chuck to define a gas-tight inner process chamber.

WO 2013/035019 A2

Declarations under Rule 4.17:

— *as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))*

— *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))*

Published:

— *without international search report and to be republished upon receipt of that report (Rule 48.2(g))*